



## P-Channel Enhancement Mode Field Effect Transistor

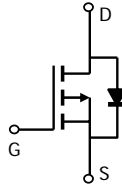
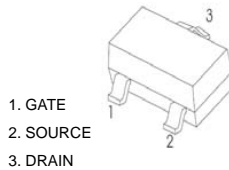
### General Description

The BC3401 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications. *Standard product BC3401 is Pb-free (meets ROHS & Sony 259 specifications). BC3401L is a Green Product ordering option. BC3401 and BC3401L are electrically identical.*

### Features

$V_{DS} (V) = -30V$   
 $I_D = -4.2 A (V_{GS} = -10V)$   
 $R_{DS(ON)} < 50m\Omega (V_{GS} = -10V)$   
 $R_{DS(ON)} < 65m\Omega (V_{GS} = -4.5V)$   
 $R_{DS(ON)} < 120m\Omega (V_{GS} = -2.5V)$

### SOT-23



### MARKING: 3401

#### Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Continuous Drain Current <sup>A</sup>	$T_A=25^\circ C$	-4.2	A
	$T_A=70^\circ C$	-3.5	
Pulsed Drain Current <sup>B</sup>	$I_{DM}$	-30	
Power Dissipation <sup>A</sup>	$T_A=25^\circ C$	1.4	W
	$T_A=70^\circ C$	1	
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	$^\circ C$

#### Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient <sup>A</sup>	$R_{\theta JA}$	65	90	$^\circ C/W$
Maximum Junction-to-Ambient <sup>A</sup>		Steady-State	85	125
Maximum Junction-to-Lead <sup>C</sup>	$R_{\theta JL}$	43	60	$^\circ C/W$



## BC3401

### Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
B <sub>V</sub> DSS	Drain-Source Breakdown Voltage	I <sub>D</sub> =-250μA, V <sub>GS</sub> =0V	-30			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =-24V, V <sub>GS</sub> =0V T <sub>J</sub> =55°C			-1 -5	μA
I <sub>GSS</sub>	Gate-Body leakage current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±12V			±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> I <sub>D</sub> =-250μA	-0.7	-1	-1.3	V
I <sub>D(ON)</sub>	On state drain current	V <sub>GS</sub> =-4.5V, V <sub>DS</sub> =-5V	-25			A
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =-10V, I <sub>D</sub> =-4.2A T <sub>J</sub> =125°C		42	50	mΩ
					75	
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-4A		53	65	mΩ
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-1A		80	120	mΩ
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =-5V, I <sub>D</sub> =-5A	7	11		S
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =-1A, V <sub>GS</sub> =0V		-0.75	-1	V
I <sub>S</sub>	Maximum Body-Diode Continuous Current				-2.2	A
<b>DYNAMIC PARAMETERS</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =-15V, f=1MHz		954		pF
C <sub>oss</sub>	Output Capacitance			115		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			77		pF
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz		6		Ω
<b>SWITCHING PARAMETERS</b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> =-4.5V, V <sub>DS</sub> =-15V, I <sub>D</sub> =-4A		9.4		nC
Q <sub>gs</sub>	Gate Source Charge			2		nC
Q <sub>gd</sub>	Gate Drain Charge			3		nC
t <sub>D(on)</sub>	Turn-On DelayTime	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-15V, R <sub>L</sub> =3.6Ω, R <sub>GEN</sub> =6Ω		6.3		ns
t <sub>r</sub>	Turn-On Rise Time			3.2		ns
t <sub>D(off)</sub>	Turn-Off DelayTime			38.2		ns
t <sub>f</sub>	Turn-Off Fall Time			12		ns
t <sub>rr</sub>	Body Diode Reverse Recovery Time		I <sub>F</sub> =-4A, dI/dt=100A/μs		20.2	
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge	I <sub>F</sub> =-4A, dI/dt=100A/μs		11.2		nC

A: The value of R<sub>θJA</sub> is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25°C. The value in any given application depends on the user's specific board design. The current rating is based on the t<sub>s</sub> ≤ 10s thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C: The R<sub>θJA</sub> is the sum of the thermal impedance from junction to lead R<sub>θJL</sub> and lead to ambient.

D: The static characteristics in Figures 1 to 6,12,14 are obtained using 80μs pulses, duty cycle 0.5% max.

E: These tests are performed with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25°C. The SOA curve provides a single pulse rating.

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## BC3401

### TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

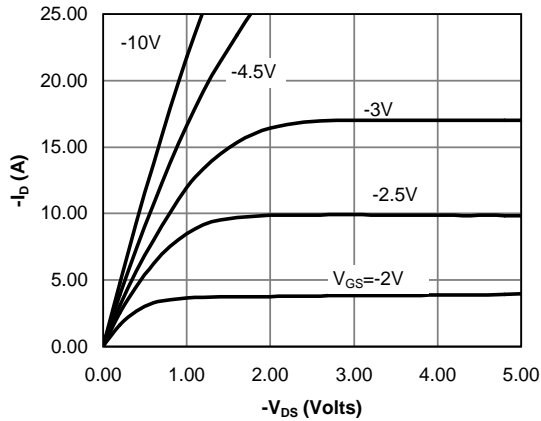


Fig 1: On-Region Characteristics

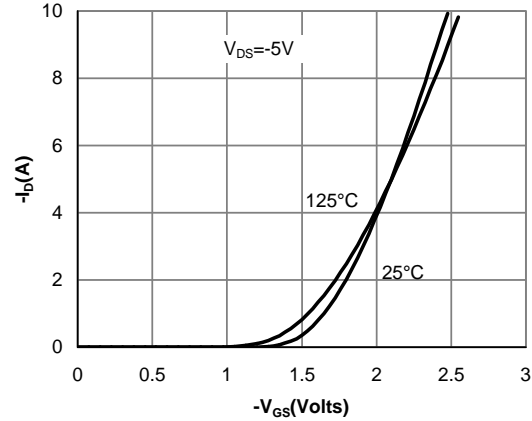


Figure 2: Transfer Characteristics

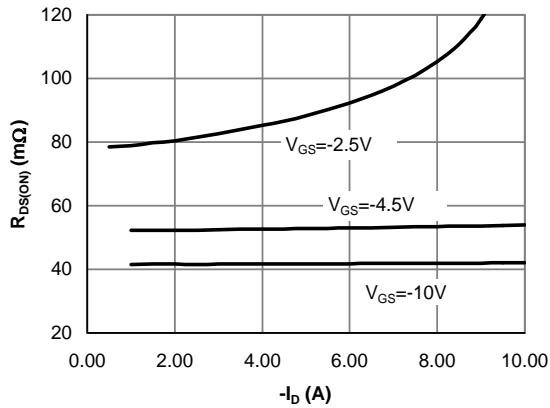


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

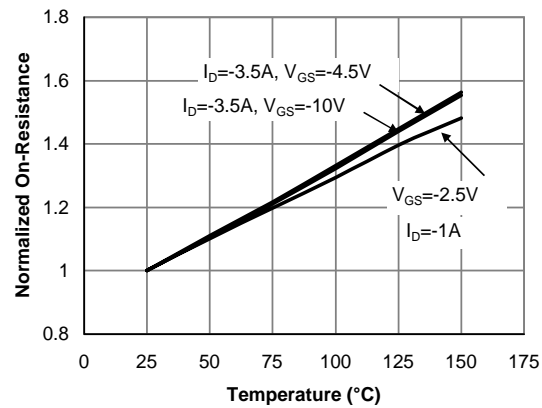


Figure 4: On-Resistance vs. Junction Temperature

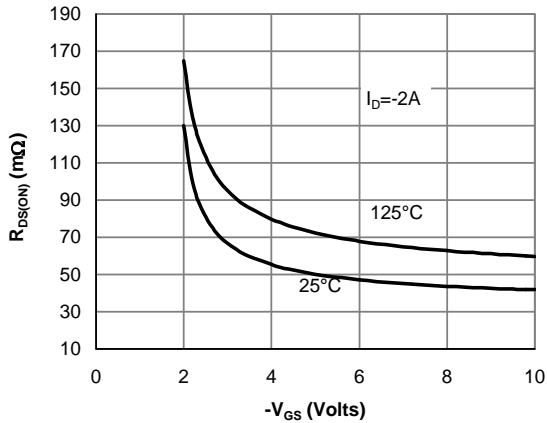


Figure 5: On-Resistance vs. Gate-Source Voltage

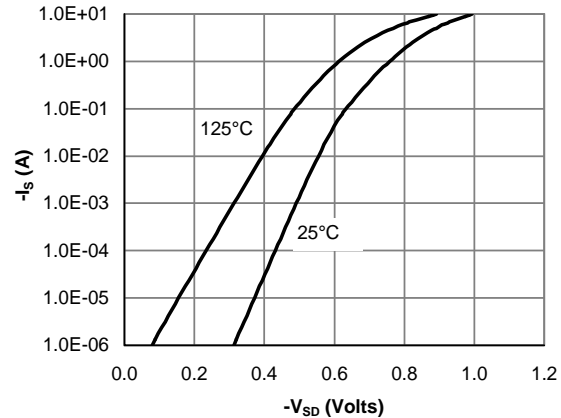


Figure 6: Body-Diode Characteristics

## BC3401

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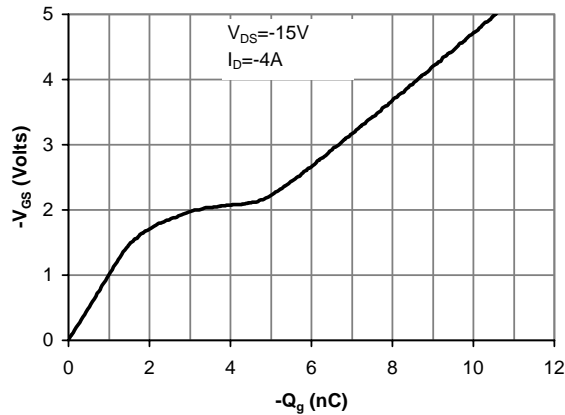


Figure 7: Gate-Charge Characteristics

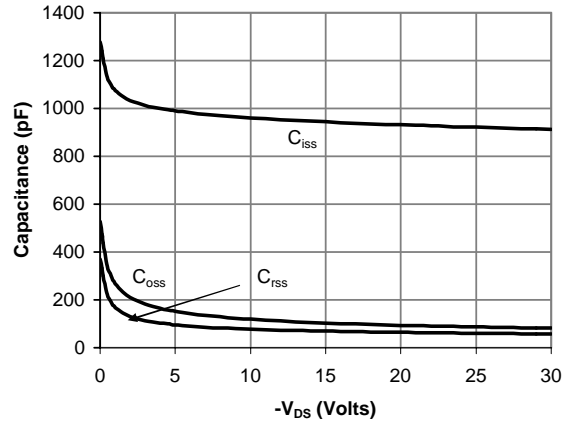


Figure 8: Capacitance Characteristics

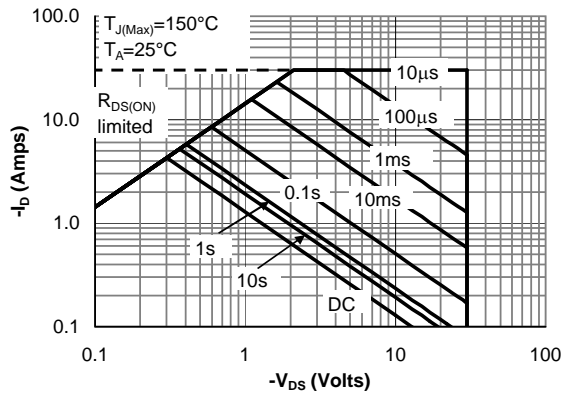


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

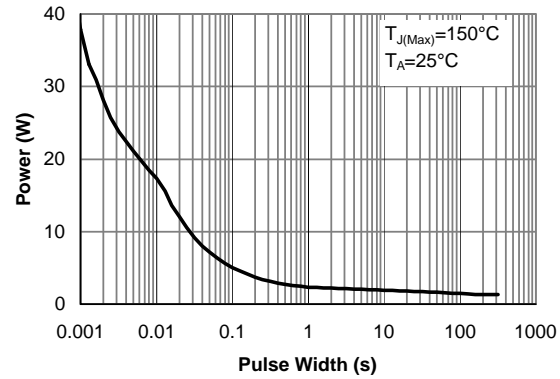


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

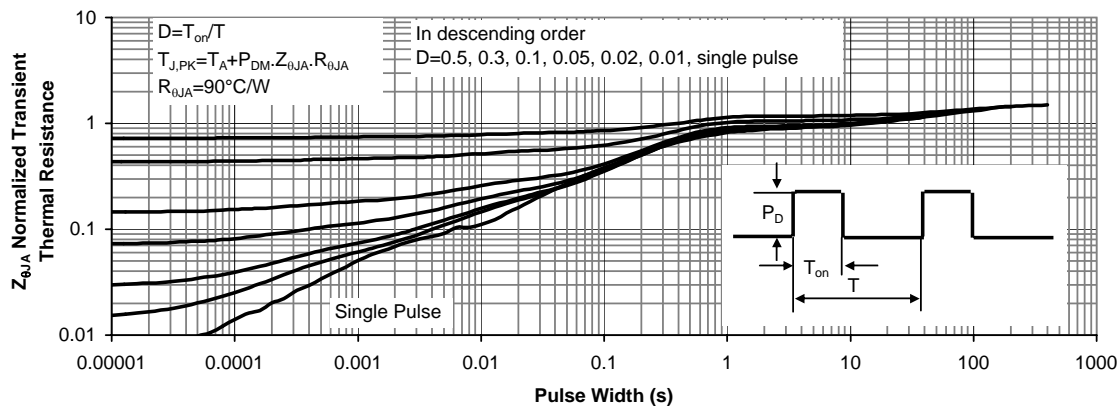


Figure 11: Normalized Maximum Transient Thermal Impedance



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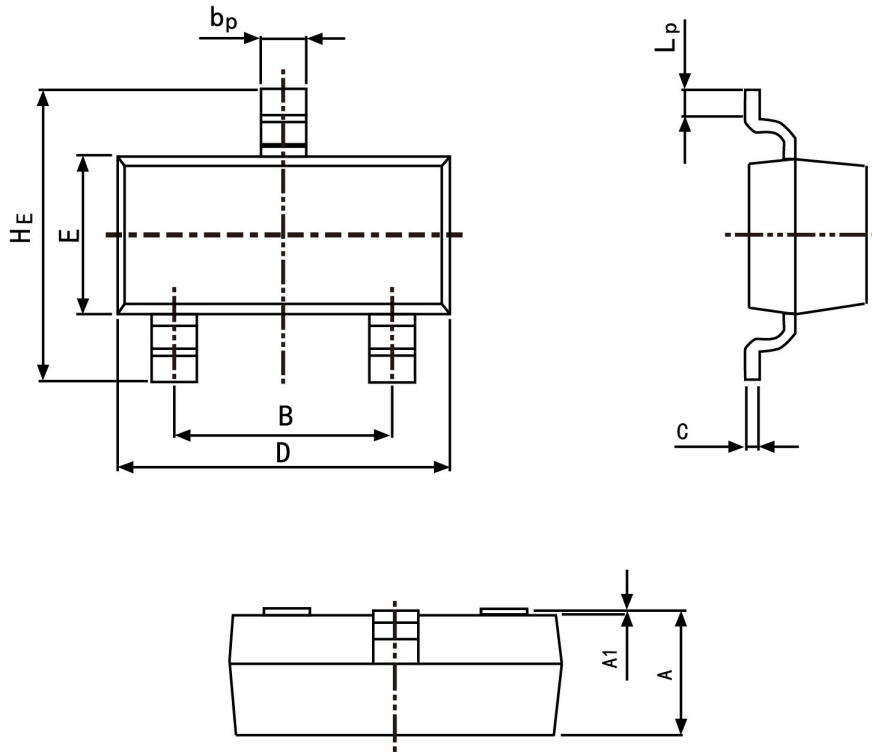


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### PACKAGE OUTLINE

Plastic surface mounted package; 3 leads

SOT-23



Symbol	Dimension in Millimeters	
	Min	Max
A	0.95	1.40
B	1.78	2.04
bp	0.35	0.50
C	0.08	0.19
D	2.70	3.10
E	1.20	1.65
HE	2.20	3.00
A1	0.100	0.013
Lp	0.20	0.50